

Title (en)

METHOD FOR PRETREATING A SURFACE OF A NON-CONDUCTING MATERIAL TO BE PLATED

Title (de)

VERFAHREN ZUR VORBEHANDLUNG EINER OBERFLÄCHE EINES MIT METALL ZU BESCHICHTENDEN NICHTLEITENDEN MATERIALS

Title (fr)

PROCEDE POUR LE PRETRAITEMENT D'UNE SURFACE D'UN MATERIAU NON CONDUCTEUR DEVANT SUBIR UNE ELECTRODEPOSITION

Publication

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Application

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Priority

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- DK PA200201429 A 20020926

Abstract (en)

[origin: WO2004029327A1] A method for pretreating a surface of a non-conducting material to be plated through precipitation of metal where an adsorbing metal oxide is initially deposited, such as MnO<sub>2</sub> or Fe<sub>2</sub>O<sub>3</sub>, on the surface, whereafter said surface is treated with a solution of transition metal ions, such as Sn<sup>++</sup> ions, and then with a solution of metal ions of a catalytic metal catalyzing chemical plating, such as a metal of the platinum group. The transition metal ions used are selected among such ions that can reduce catalytic metal ions into catalytic metal. The method renders it possible to plate non-conducting materials, such as plastic materials, which cannot or only with great difficulty can be plated by a conventional activation by means of colloidal palladium.

IPC 8 full level

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